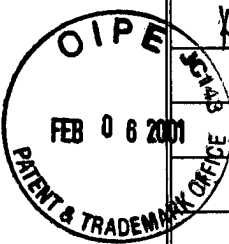
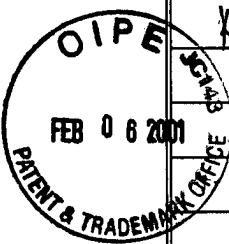
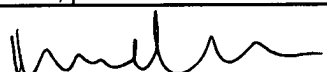
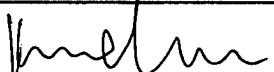


INFORMATION DISCLOSURE CITATION PTO-1449				ATTY. DOCKET NO. P1D1C1		APPLICATION NO. 09/245,499			
				APPLICANT Igor Y. Khandros				#25	
				FILING DATE February 5, 1999		GROUP 2841			
U.S. PATENT DOCUMENTS									
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE			
	5,090,119	2/92	Tsuda et al.	29	843				
	3,119,172	1/64	Mazenko et al.	29	155.5				
	3,734,386	5/73	Hazel	228	5				
	2,429,222	10/4	Erhardt et al.	204	28				
	5,195,237	3/93	Cray et al.	29	838				
	4,418,857	12/83	Ainslie et al.	228	124				
	4,983,907	1/91	Crowley	324	158 F				
	5,055,780	10/91	Takagi et al.	324	158 F				
	5,187,020	2/93	Kwon et al.	428	601				
FOREIGN PATENT DOCUMENTS									
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation			
						Yes	No		
	4-65840	3/92	Japan	H01L	21/60		✓		
	0 002 166	5/79	Europe	H01L	23/32		✓		
	0 396 248	11/90	Europe	H01R	13/04		✓		
	WO94/03036	3/94	PCT	H05K	3/36		✓		
	DE 31 29 568	4/82	Germany	H01L	23/50		✓		
	60-150657	08/85	Japan	257	781		✓		
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)									
he	Ando, et al., "Plating micro bonding used for Tape Carrier package", Abstracts, NIST, VLSI Packaging Workshop, October 11-13, 1993, Yorktown Heights, NY, 1 page total.								
he	"Bimetal VLSI Chip Interconnections", IBM Technical Disclosure Bulletin, April 29, 1987, No. 11, Armonk, NY USA, 2 pages total.								
he	"Corrosion Protection for Incusil Brazed Joints on Modules", IBM Technical Disclosures, Vol. 19, No. 6, p. 2059.								
EXAMINER 				DATE CONSIDERED 3/23/01					

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

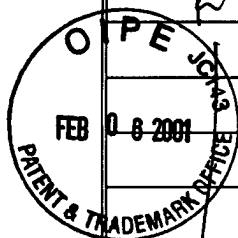
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				APPLICANT Igor Y. Khandros			
				FILING DATE February 5, 1999		GROUP 2841	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
ke	4,522,893	6/85	Bohlen, et al.	428	641		
	3,795,037	3/74	Luttmer	29	628		
	4,545,610	10/85	Lakritz et al.	29	589		
	5,130,779	7/92	Agarwala et al	357	67		
	5,476,211	12/95	Khandros	228	180.5		
	4,780,836	10/88	Miyazaki et al.	364	551.01		
	5,047,711	9/91	Smith et al.	324	158		
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
ke	0314287	6/91	Japan	H01L	21/60		✓
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
EXAMINER				DATE CONSIDERED			
				3/23/01			

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

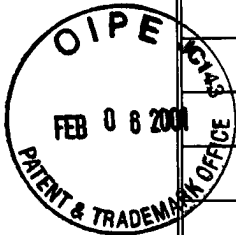
U.S. PATENT DOCUMENTS

4,615,573	10/86	White et al.	339	17M	
3,672,047	6/72	Sakamoto et al.	29	628	
5,455,390	10/95	DiStefano et al.	174	262	Feb-94
3,844,909	10/74	McCary et al.	204	40	
3,373,481	3/68	Lins et al.	29	471.3	
3,460,328	8/69	Christy et al.	29	481	
3,509,270	4/70	Dube et al.	174	68.5	
3,616,532	11/71	Beck	29	625	
4,067,104	1/78	Tracy	29	626	
4,295,700	10/81	Sado	339	61	
4,330,165	5/82	Sado	339	59	
4,532,152	7/85	Elarde	427	96	
4,642,889	2/87	Grabbe	29	740	
4,764,848	8/88	Simpson	361	408	
4,777,564	10/88	Derfiny et al.	361	405	
4,793,814	12/88	Zifcak et al.	439	66	
4,821,148	4/89	Kobayashi et al.	361	392	
4,860,433	8/89	Miura	29	605	
4,893,172	1/90	Matsumoto et al.	357	79	
4,914,814	4/90	Behum et al.	29	843	
4,955,523	9/90	Calomagno et al.	228	179	
4,989,069	1/91	Hawkins et al.	357	74	
5,086,337	2/92	Noro et al.	357	74	
5,110,032	5/92	Akiyama et al.	228	102	
5,130,779	7/92	Agarwala et al.	357	67	
5,366,380	11/94	Reymond	439	66	Mar-93
5,386,344	1/95	Beaman et al.	361	785	Jan-93
4,784,872	11/88	Mueller et al.	427	96	
5,148,968	9/92	Schmidt et al.	228	180.2	
4,878,611	11/89	Lo Vasco et al.	228	246	
5,154,341	10/92	Melton et al.	228	254	



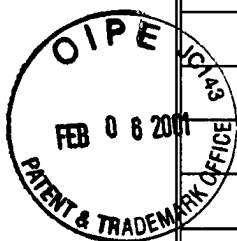
U.S. PATENT DOCUMENTS

KC	4,332,341	6/82	Minetti et al.	228	188	
	4,664,309	5/87	Allen et al.	228	563	
	5,627,406	5/97	Pace	257	700	Aug-96
	3,747,198	7/73	Benson et al.	257	784	
	3,087,239	4/63	Clagett et al.	257	784	
	3,787,966	1/74	Klessika et al.	257	784	
	5,296,744	3/94	Liang et al.	257	784	Jun-92
	5,359,227	10/94	Liang et al.	257	784	Dec-93
	5,606,196	2/97	Lee et al.	257	503	Dec-95
	4,618,879	10/86	Mizukoshi et al.	257	784	
	5,536,973	7/96	Yamaji et al.	257	784	
	5,396,104	3/95	Kimura et al.	257	784	Nov-90
	5,639,558	6/97	Tatsumi et al.	428	458	Mar-95
	5,656,830	8/97	Zechman et al.	257	784	Oct-92
	5,091,772	2/92	Kohara et al.	257	784	
	3,519,890	7/70	Ashby	361	776	
	4,385,341	5/83	Main	361	776	
	4,728,751	3/88	Canestate	361	776	
	5,349,495	9/94	Visel et al.	361	774	Oct-90
	5,389,743	2/95	Simila et al.	174	262	
	4,996,629	2/91	Christiansen et al.	361	776	
	3,982,811	9/76	Siu et al.	439	884	
	5,298,464	3/94	Schlesinger et al.	437	216	May-92
	5,598,627	2/97	Saka et al.	29	861	Jun-95
	5,621,263	4/97	Kaida	310	333	Aug-94
	5,239,126	8/93	Oshiba	174	35R	
	3,445,770	5/69	Harmon	324	762	
	3,849,728	11/74	Evans	324	762	
	5,055,778	10/91	Okubo et al.	324	762	
	5,585,737	12/96	Shibata	324	754	Dec-94
	5,534,784	7/96	Lunn et al.	324	757	May-94
	5,506,498	4/96	Anderson et al.	324	158.1	Mar-95
	5,436,571	7/95	Karasawa	324	765	Apr-94



U.S. PATENT DOCUMENTS

ke	5,338,223	8/94	Melatti et al.	439	482	Oct-92
	5,220,277	6/93	Reitinger	324	158F	
	5,130,644	7/92	Ott	324	58F	
	4,961,052	10/90	Tada et al.	324	158P	
	4,899,099	2/90	Mendenhall et al.	324	158F	
	4,727,319	2/88	Shahriary	324	158P	
	5,532,609	7/96	Harwood et al.	324	754	Apr-95
	5,457,398	10/95	Schwindt et al.	324	754	Aug-93
	5,325,052	6/94	Yamashita	324	158P	Sep-92
	5,303,938	4/94	Miller et al.	279	3	Mar-93
	5,266,889	11/93	Harwood et al.	324	158F	May-92
	5,198,752	3/93	Miyala et al.	324	158F	
	5,247,250	9/93	Rios	324	158F	
	5,214,375	5/93	Ikeuchi et al.	324	158F	Mar-92
	4,998,062	3/91	Ikeda	324	158F	
	4,985,676	1/91	Karasawa	324	158F	
	4,870,356	9/89	Tingley	324	158F	
	5,534,786	7/96	Kaneko et al.	324	760	Feb-95
	5,479,108	12/95	Cheng	324	765	Nov-92
	5,568,056	10/96	Ishimoto	324	754	Nov-94
	5,559,444	9/96	Farnworth et al.	324	754	May-95
	5,488,292	1/96	Tsuta	324	158.1	Oct-93
	5,410,162	4/95	Tigelaar et al.	257	048	Oct-93
	5,355,081	10/94	Nakata et al.	324	765	May-93
	5,329,228	7/94	Comeau	324	765	Jul-92
	5,140,405	8/92	King et al.	357	67	
	4,567,433	1/86	Ohkubo et al.	324	158P	
	4,697,143	9/87	Lockwood et al.	324	158P	
	4,746,857	5/88	Sakai et al.	324	158F	
	4,764,723	8/88	Strid	324	158P	
	5,424,651	6/95	Green et al.	324	754	Mar-92
	5,389,873	2/95	Ishii et al.	324	158.1	May-93
	5,559,446	9/96	Sano	324	760	Jul-94



U.S. PATENT DOCUMENTS

✓	5,550,482	8/96	Sano	324	758	Jul-94
	5,510,724	4/96	Itoyama et al.	324	760	May-94
	5,444,366	8/95	Chiu	324	158.1	Feb-94
	5,517,126	5/96	Yamaguchi	324	758	Jul-93
	5,555,422	9/96	Nakano	324	754	Oct-95
	3,849,872	11/74	Hubacher	29	574	
	5,363,038	11/94	Love	324	158.1	Aug-92
	4,038,599	7/77	Bove et al.	324	158F	
	5,391,984	2/95	Worley	324	158.1	Nov-91
	5,444,386	8/95	Mizumura	324	754	Jan-93
	5,479,109	12/95	Lau et al.	324	758	Jan-94
	5,440,241	8/95	King et al.	324	765	Mar-92
	5,532,614	7/96	Chiu	324	763	Apr-95
	5,336,992	8/94	Saito et al.	324	754	Jun-92
	5,483,175	1/96	Ahmad et al.	324	766	Mar-94
	5,446,395	8/95	Goto	324	763	Sep-93
	5,461,328	10/95	Devereaux et al.	324	765	Jul-93
	5,397,997	3/95	Tuckerman et al.	324	754	May-93
	5,457,400	10/95	Ahmad et al.	324	763	Jul-93
	5,070,297	12/91	Kwon et al.	324	158	
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	5,497,079	3/96	Yamada et al.	324	158	Aug-93
	5,532,610	7/96	Tsujide et al.	324	757	Aug-94
	5,570,032	10/96	Adkins et al.	324	760	Aug-93
	4,899,107	2/90	Carbett et al.	324	158	
	5,073,117	12/91	Malhi et al.	439	71	
✓	5,601,740	2/97	Eldridge et al.	219	130	Dec-95

